GAS TREATMENT METHOD AND GAS TREATMENT DEVICE

ABSTRACT

In the present invention, a gas treatment method for implementing gas treatment on a substrate having recesses includes disposing a substrate having recesses inside a chamber, supplying gas for pressure adjustment inside the evacuated chamber and raising the pressure inside the chamber to perform pressure regulation to a predetermined pressure, and subsequently, causing a treatment reaction using the treatment gas inside the chamber to perform gas treatment on the side walls of the recesses of the substrate. Treatment gas for causing the treatment reaction is used as at least a portion of the pressure adjustment gas when implementing pressure regulation.

(Fig. 11)